

Please amend the paragraph starting at p. 10, line 26 as follows:

A blend of dielectric material may be prepared by providing a resin such as epoxy, optionally including dielectric or insulating particles such as barium titanate, and optionally including a catalyst for the epoxy. Absorbed water or residual materials on the particles; e.g., carbonates resulting from the manufacturing process can be removed from the surface of the particles before use by heating the particles in air at a particular temperature for a period of time, for example, 350°C for 15 hours. After heating, the particles may be stored in a dessicator prior to use in the blend.

In the Claims:

Please amend the claims as follows:

*OLD C3*

1. (Thrice Amended). An electronic package, comprising:
  - a conductive trace layer having a first side and a second side, the conductive trace layer being patterned to define a plurality of interconnect pads;
  - a dielectric substrate mounted on the first side of the conductive trace layer;
  - an internal capacitor having a capacitance of from about 1 nF/sq.cm. to about 100 nF/sq.cm. including a first conductive layer, a second conductive layer and a layer of dielectric material made of a non-conductive polymer blended with high dielectric constant particles disposed between the first and the second conductive layers, the first conductive layer attached to the second side of the conductive trace layer by a first adhesive layer;
  - a plurality of interconnect regions extending through the first conductive layer and the dielectric material layer of the capacitor; and
  - an interconnect member connected between each of the conductive layers of the capacitor and a corresponding set of the interconnect pads, the first conductive layer of the capacitor being electrically connected to a first set of the interconnect pads and the second conductive layer of the capacitor being electrically connected to a second set of the interconnect pads, the interconnect members corresponding to the second set of interconnect pads extending through one of the interconnect regions.